



Press Announcement

SET introduces Innovative Patented Chamber for Removal of Oxide.

Saint-Jeoire, France, October 18, 2010 – Today SET unveils a patented system enabling a thorough removal of oxides before or during the bonding sequence. Addressing the challenges of the oxidation of metal surfaces in device bonding, this machine system encompasses a substrate chuck and a bond head with a non contact localized confinement chamber which operates safely with reducing gases such as forming gas or formic acid vapor. It can be implemented on any new SET bonder models FC150 and FC300.

To preserve the standard capabilities of SET's bonding tools and especially the low contact force measurement applied to the components, the "Semi-Open" Confinement Chamber has no hardware sealing. A non-contact virtual seal of the micro-chamber enables gas confinement for chip-to-chip or chip-to-wafer bonding under controlled atmosphere; it ensures gas collection and prevents oxygen intrusion while preserving the alignment of the device with respect to its substrate. Consequently, it ensures an excellent wetting and a higher quality of solder joints at reduced bonding forces and temperatures as well as higher yield as no cleaning step is required.

This technology breakthrough is a perfect answer to overcome the bonding challenges of demanding applications using AuSn and Indium, such as optoelectronics assembly (laser bar, VCSELs) and imaging sensors (IR-FPA).

About SET

SET, Smart Equipment Technology, is a world leading supplier of High Accuracy Die-to-Die, Die-to-Wafer Bonding and Nanoimprint Lithography solutions. With more than 300 Device Bonders installed worldwide, SET is globally renowned for the unsurpassed placement accuracy and the high flexibility of its Flip Chip bonders. From the KADETT semi-automated R&D Device Bonder to the automated FC150 and FC300, SET offers a continuous process path from research to production. SET bonders cover most bonding technologies and offer the unique ability to handle and bond both fragile and small components onto substrates up to 300 mm. SET is a wholly owned subsidiary of Replisaurus Technologies. Further information is available on www.set-sas.fr.

#

SET contacts:

Gilbert Lecarpentier
Business Development Manager
Mobile: +33 (0) 686 28 12 24
Phone: +33 (0) 450 35 83 92
gilecarpentier@set-sas.fr

Emmanuelle Grenèche
Marcom Service
Phone: +33 4 50 35 38 09
egreneche@set-sas.fr